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Block Diagram

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50 Pin Connector to EVM Board, Hot Swap controller, EEPROM

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Isolated SPI & I2C, Isolated Fly buck Power Supply for +18V\_ISO, -18V\_ISO, +6V\_ISO and 3.3V\_NON\_ISO

Page 5  
LDO to generate +5V\_ISO and VCC & ADC

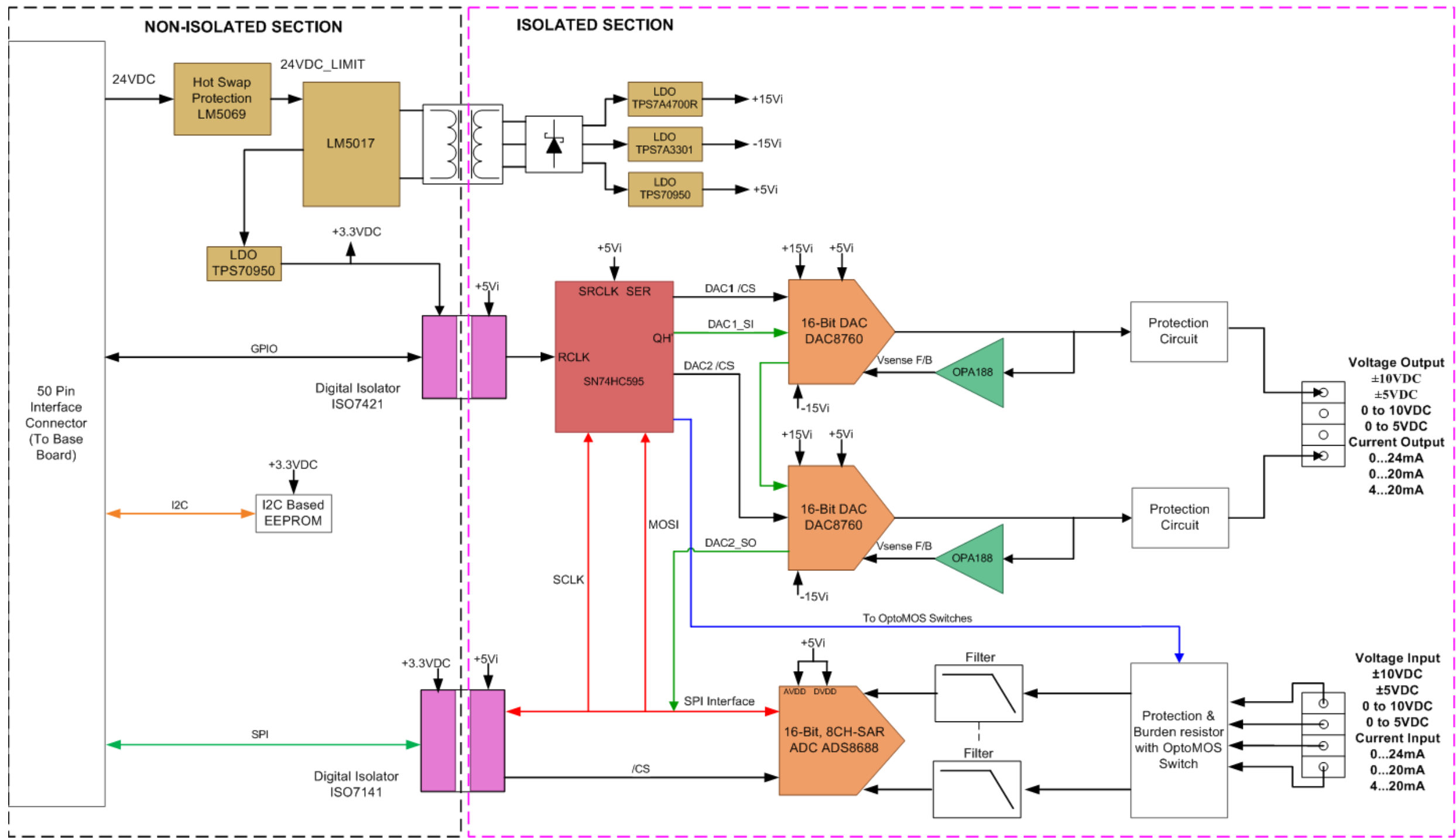
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Analog Input 1

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Analog Input 2

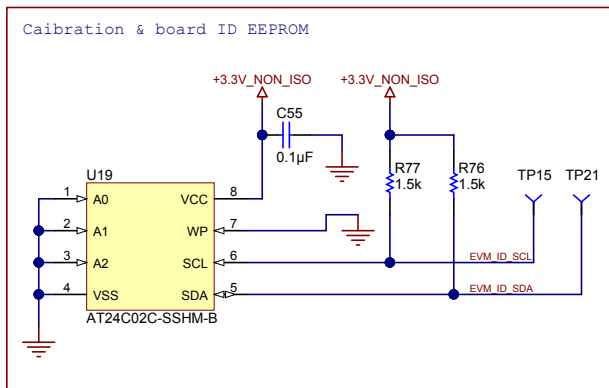
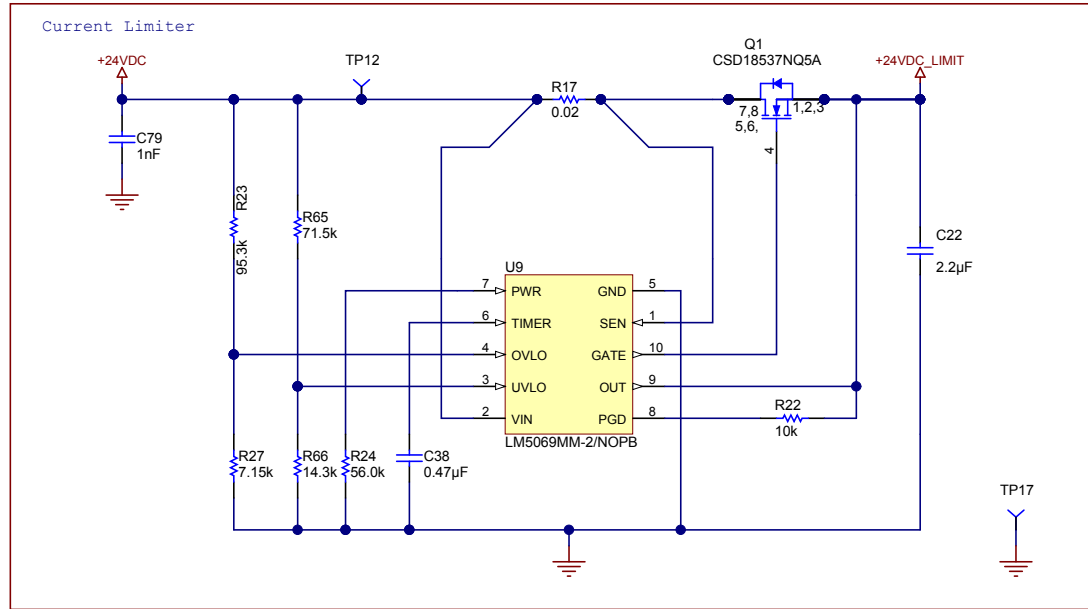
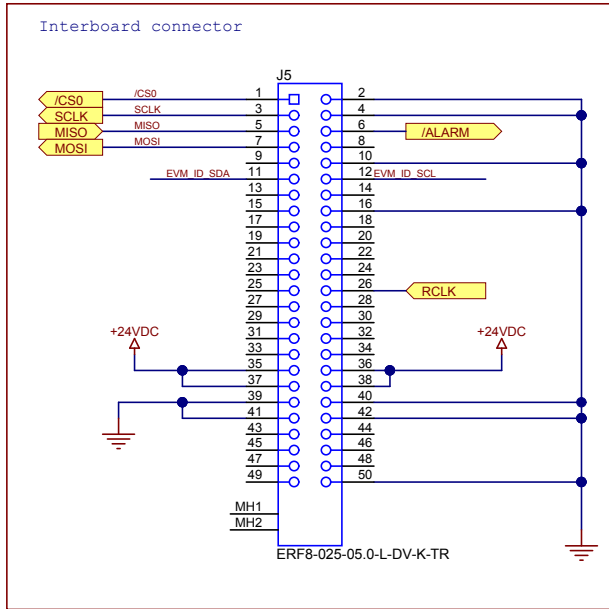
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Mounting holes, Fiducials Marking

Revision History	
Revision	Notes

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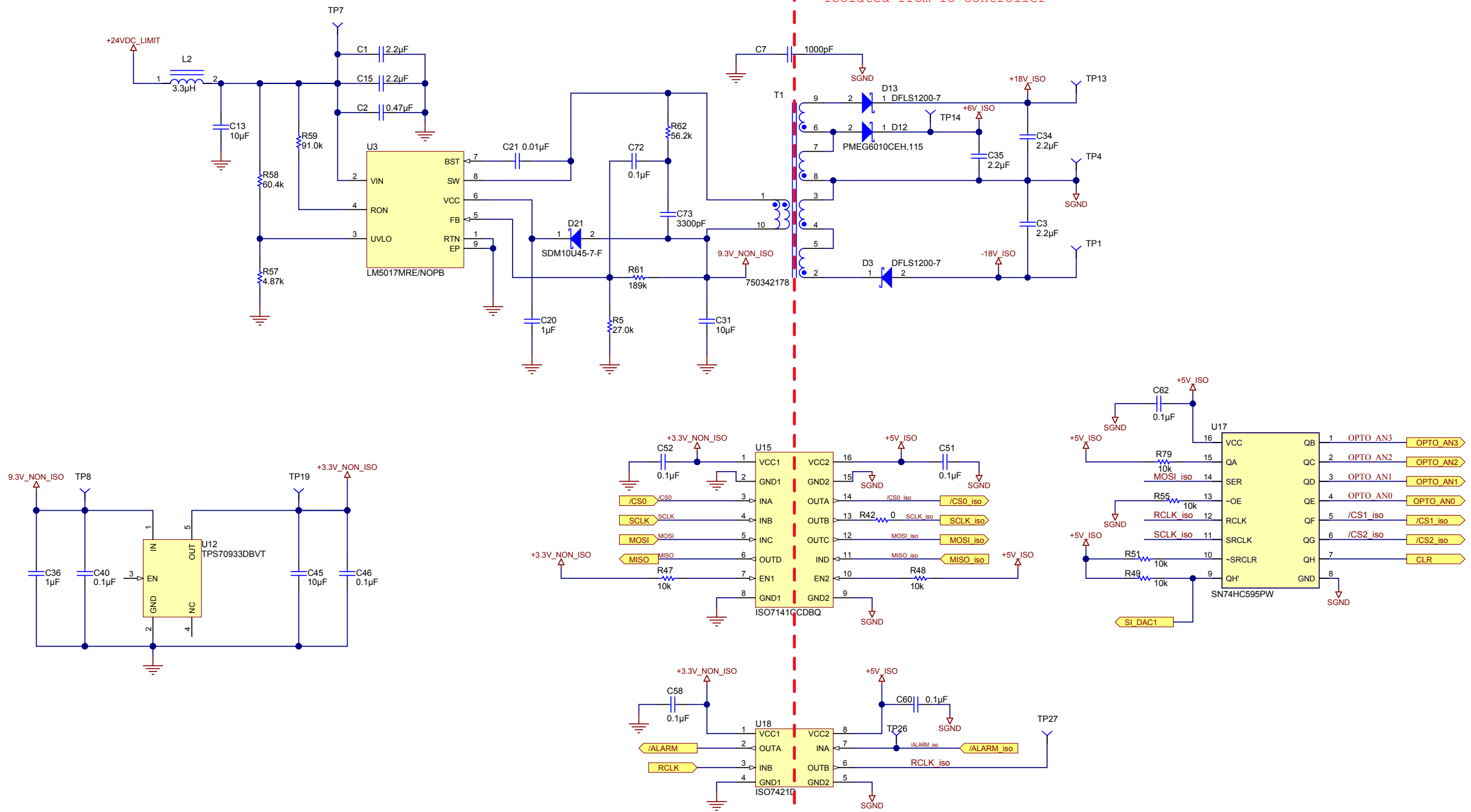
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Number: TIDA-00170	Rev: E1	Designed for: Public Release	Mod. Date: 6/20/2014
SVN Rev: Not in version control	Assembly Variant: [No Variations]	Project Title: Analog Input Output Module	Sheet Title:
Drawn By: Amol Gadkari	File: Pg3 Interboard conn, HS & EEPROM.SchDoc	Sheet: 3 of 8	Size: B
Engineer: Amol Gadkari	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>		



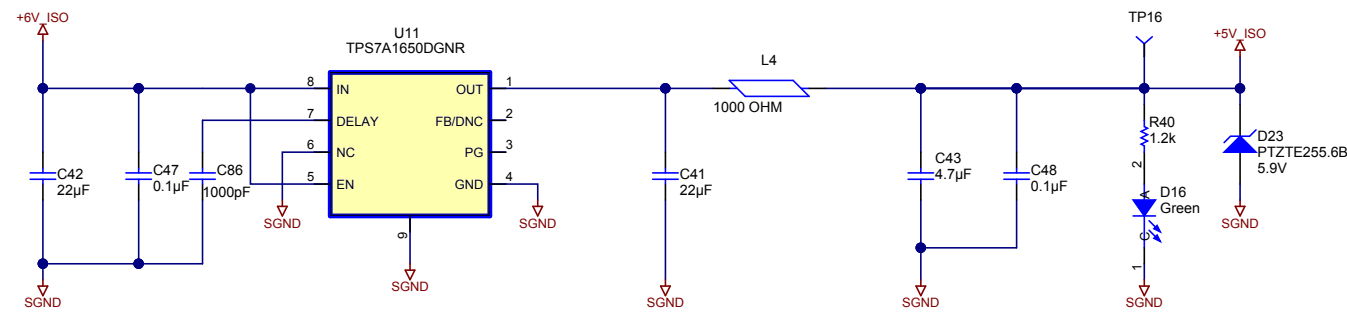
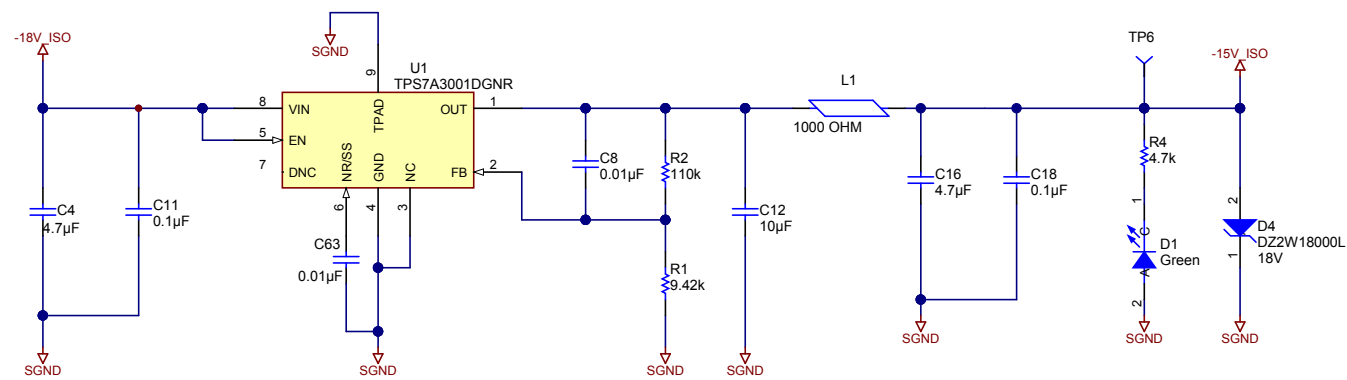
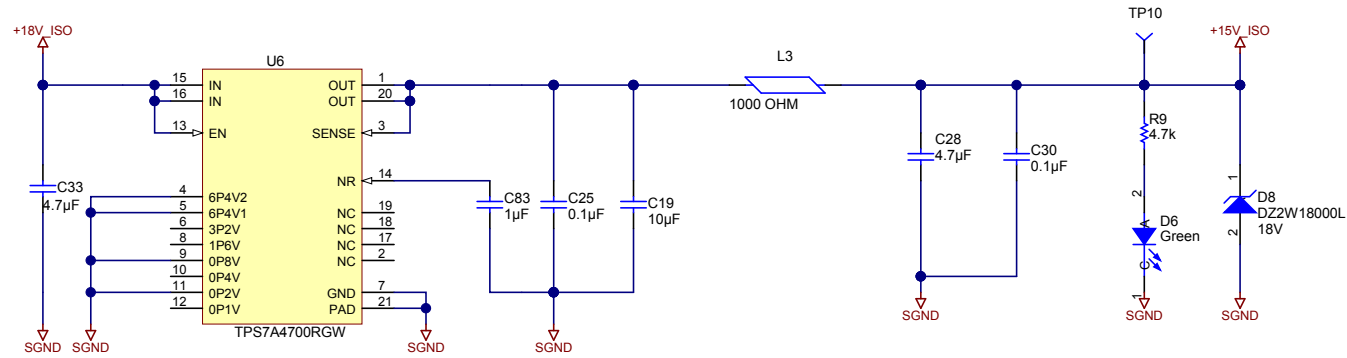
Isolated power supply and Signal Isolation

Isolated from IO controller



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LDO

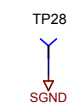
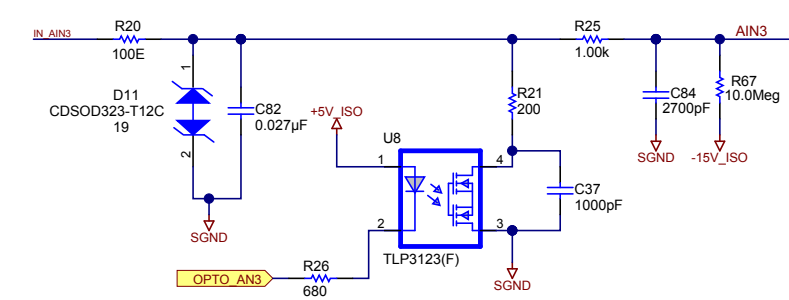
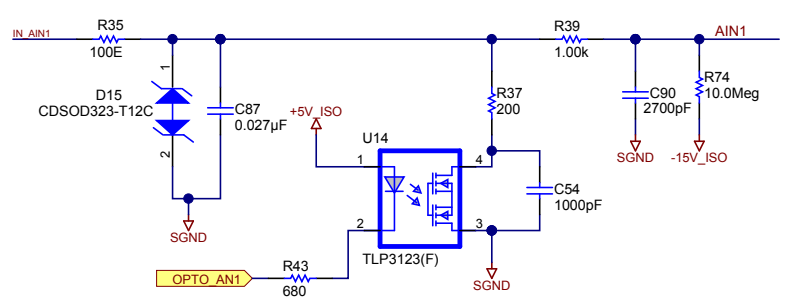
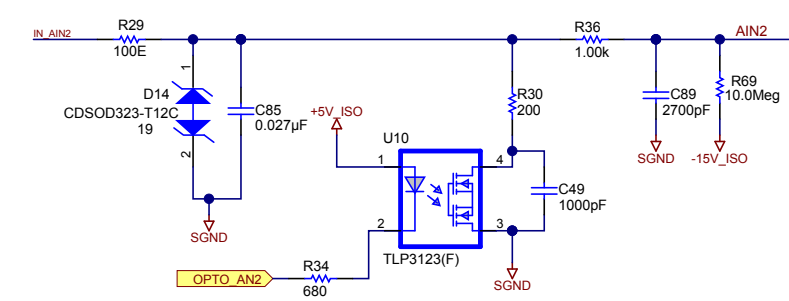
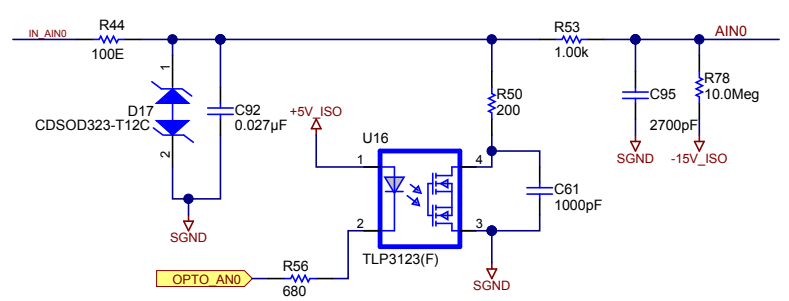
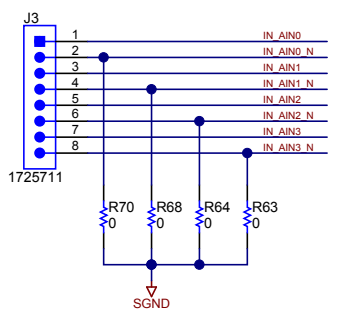
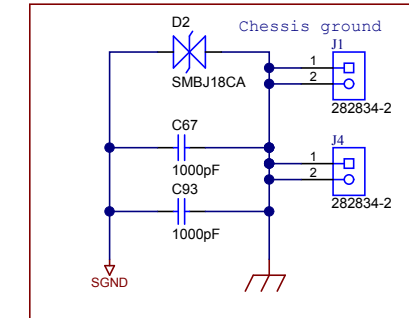
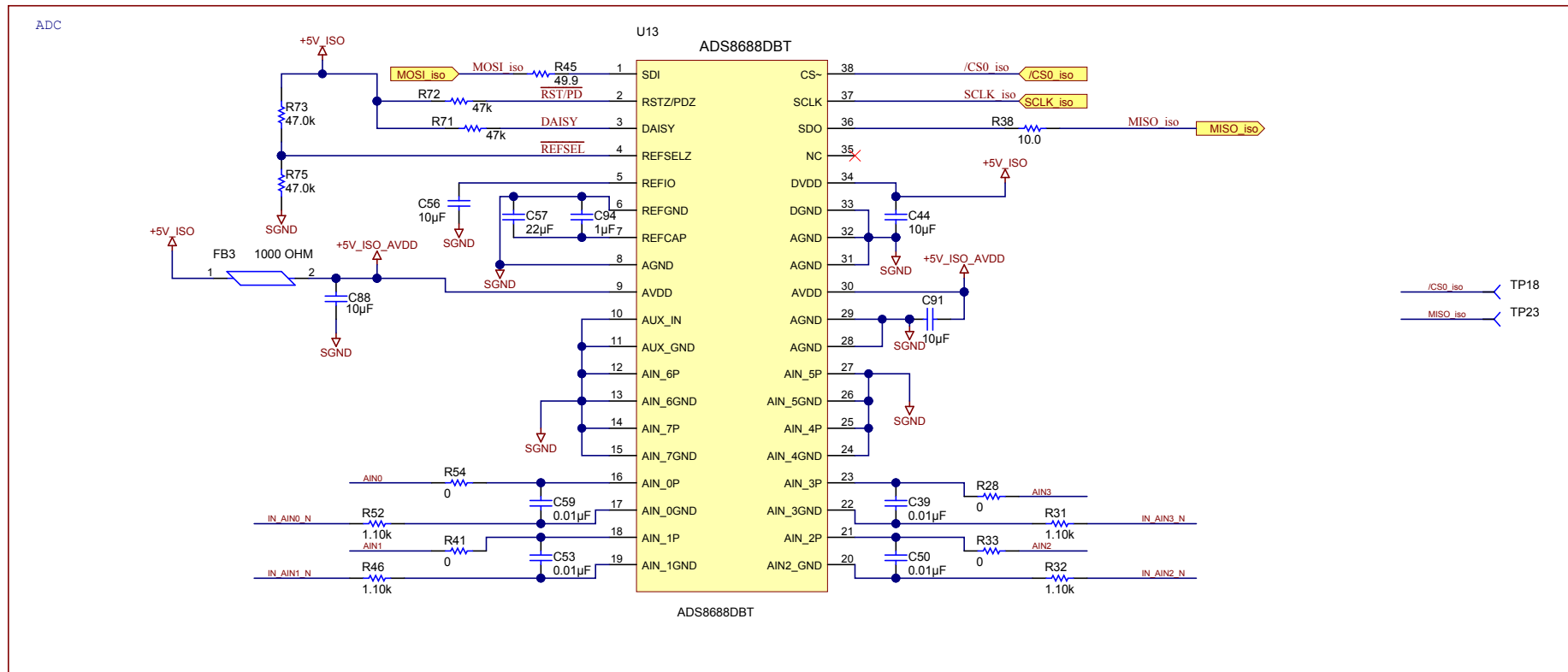


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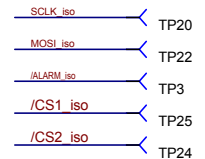
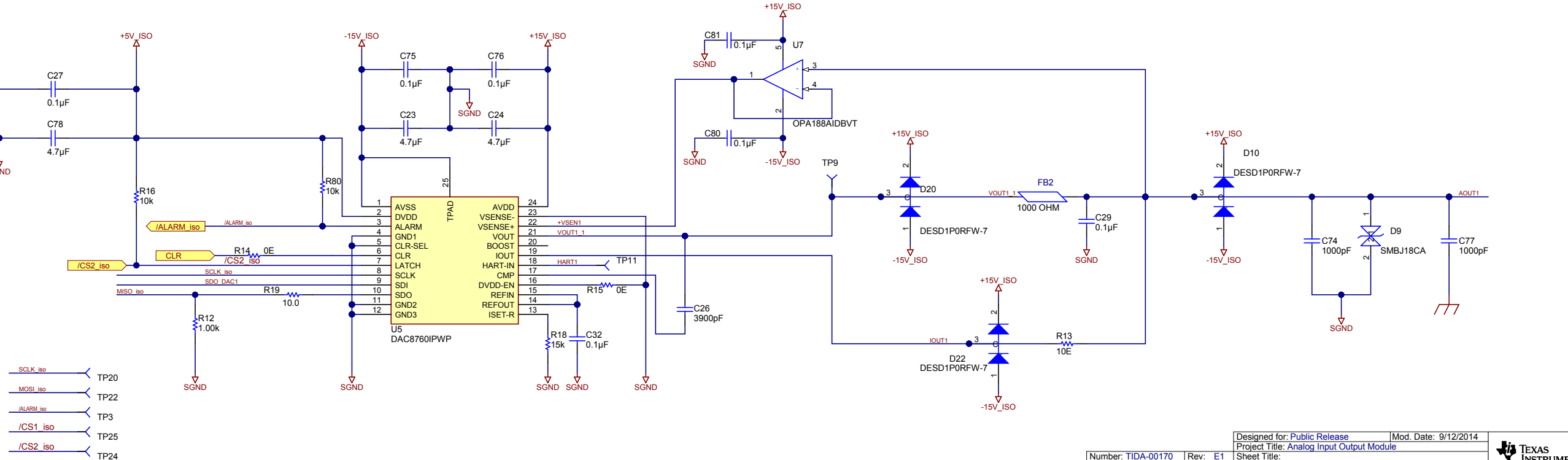
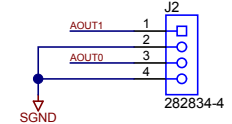
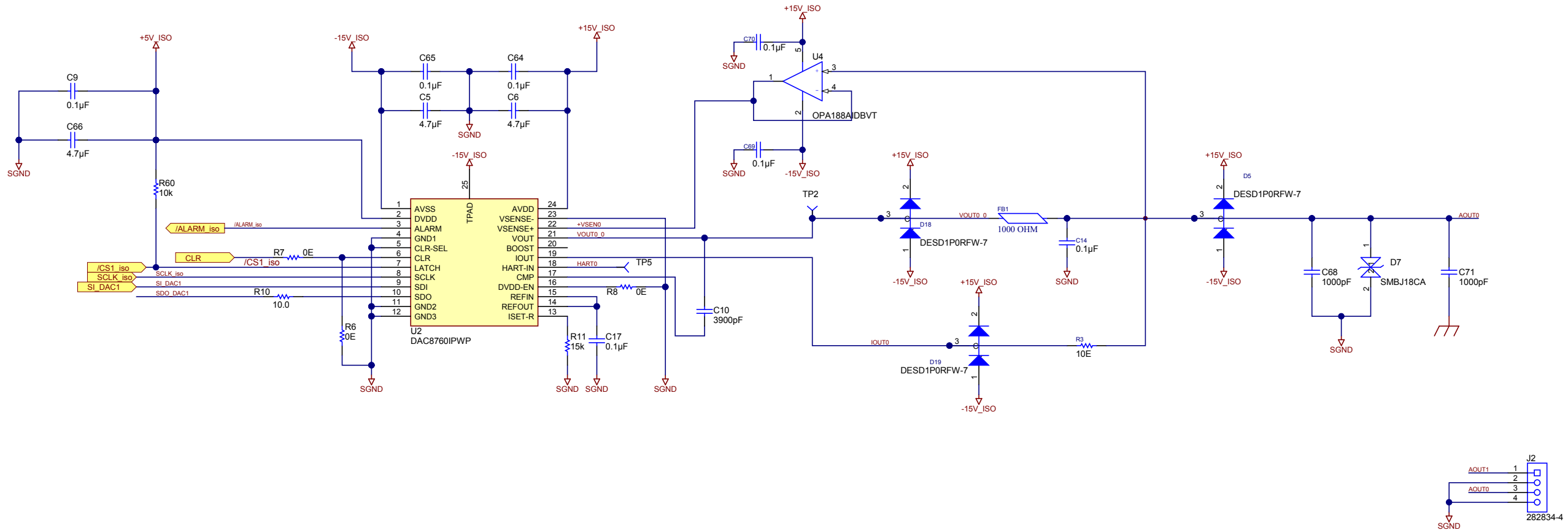
Designed for: Public Release	Mod. Date: 9/12/2014
Project Title: Analog Input Output Module	
Number: TIDA-00170	Rev: E1
SVN Rev: Not in version control	Sheet Title:
Drawn By:	Assembly Variant: [No Variations]
Engineer: Amol Gadkari	File: Pg5 LDO.SchDoc
	Sheet: 5 of 8
	Size: B
	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>



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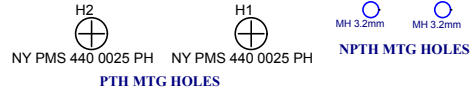


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Fiducials



Mounting holes



PCB Number: TIDA-00170  
PCB Rev: E1

PCB  
LOGO  
Texas Instruments

LBL1

PCB Label  
Size: 0.65" x 0.20"

ZZ1

Label Assembly Note  
This Assembly Note is for PCB labels only

ZZ2

Assembly Note  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3

Assembly Note  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4

Assembly Note  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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Designed for: <b>Public Release</b>		Mod. Date: 6/20/2014	
Project Title: <b>Analog Input Output Module</b>			
Number: <b>TIDA-00170</b>	Rev: <b>E1</b>	Sheet Title:	
SVN Rev: <b>Not in version control</b>		Assembly Variant: <b>[No Variations]</b>	Sheet: <b>8</b> of <b>8</b>
Drawn By:		File: <b>Pg9 Hardware.SchDoc</b>	Size: <b>B</b>
Engineer: <b>Amol Gadkari</b>		Contact: <b>http://www.ti.com/support</b>	



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